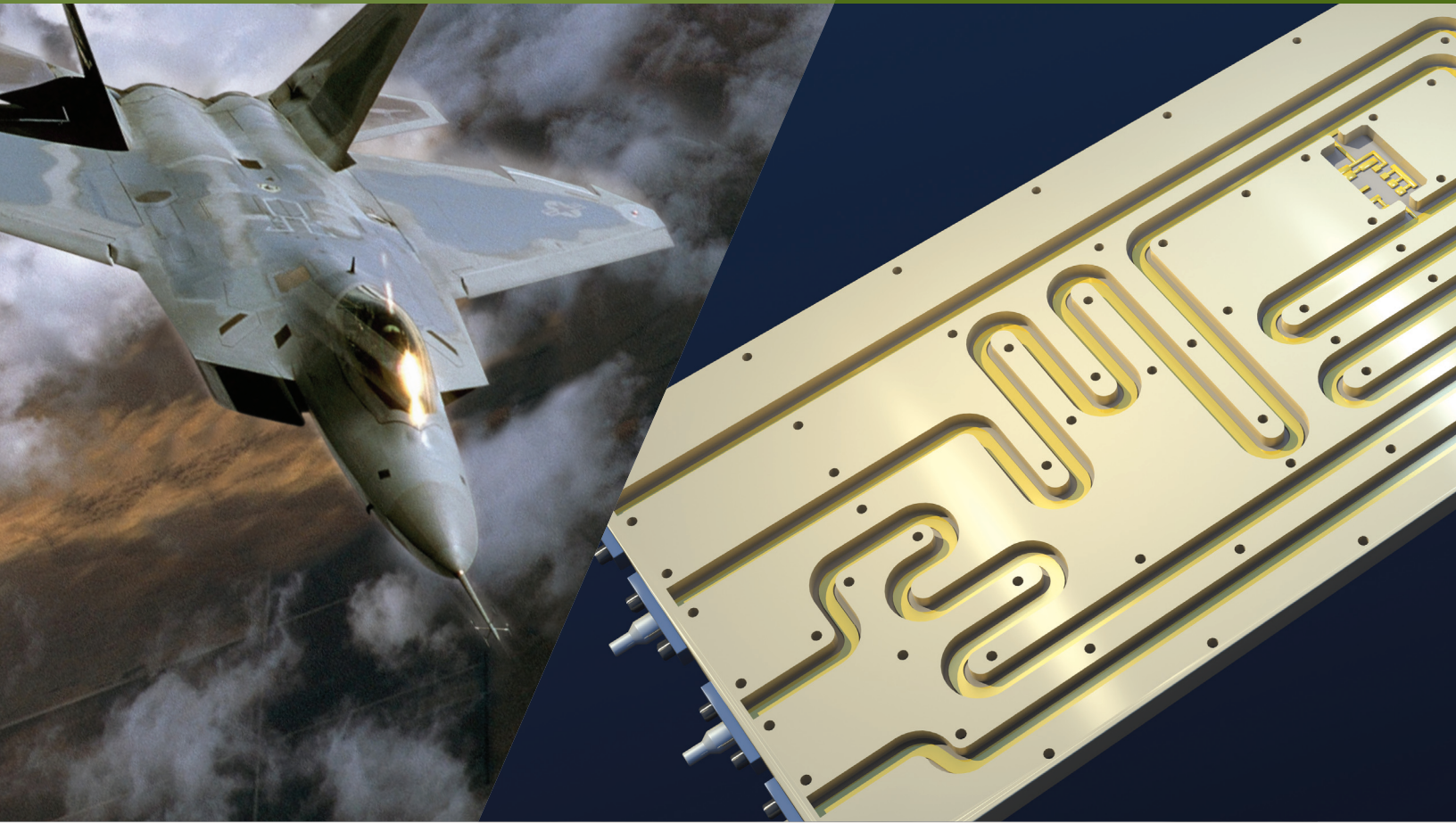


# Rockwell Collins Printed Circuits



## Precise leading-edge technology.

Rockwell Collins Printed Circuits offers Printed Circuit Board product that satisfy the highest standards of military, telecommunications, and instrumentation industries. Our history of expertise in avionics, communications and manufacturing uniquely qualifies us to meet the most rigid industry standards for our customers.

By leveraging our 40 years of history of world-class printed circuit manufacturing and quality, Rockwell Collins Printed Circuits assures we will meet your exacting specifications.

We are your trusted printed circuit board (PCB) fabrication resource.

## KEY FEATURES

- ▶ Primarily address high technology, complex, and specialty printed circuit board market
- ▶ Focus is on low to medium volume quantity
- ▶ Standard technologies
  - 8 - 30 layers standard material
  - 2 - 12 layers specialty materials
  - Blind and buried vias
  - Sequential lamination
  - Standard materials
    - FR-4
    - Polyimide
    - BT
  - Specialty
    - Mixed dielectric
    - Rogers
    - Taconic
    - Arlon
- Final finish
  - Immersion silver
  - Immersion tin
  - Electroless nickel/immersion gold
  - Electroplated nickel/gold
  - Tin lead plated
  - HASL
- Heatsink assemblies
- Heavy copper
- Controlled impedance
- Copper invar copper

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## INNOVATIVE TECHNOLOGIES

- › Fine circuit trace - .002" (review required)
- › Small plated hole - .006"
- › Microvia
- › RF AccuBond™
  - "Void Free" PCB to metal pallet bonding
  - Metal fused bond line
  - Reduction or elimination of associated tuning requirements and costs
  - Superior grounding versus adhesive bonding
  - Excellent thermal dissipation
  - Consistent electrical performance
  - Competitively priced
  - Applications
    - Flat surface pallets
    - Multi-planar pallets with PCB in pallet cavities
    - PCBs bonded to one or both sides
  - Alternative and superior to other bonding processes:
    - Sweat soldering
    - Metalback PCBs
    - Adhesive bonding films

## KEY BENEFITS

- › Design definition and review
- › Prototype development
- › Design for manufacturability (DFM)
- › Value engineering
- › Quality engineering
- › Statistical process control
- › Inventory management
- › Electronic data exchange
- › Comprehensive ramp-to-manufacturing services

## FACILITY

Rockwell Collins operates from a state-of-the-art 65,000 sq ft manufacturing facility that is part of the Rockwell Collins 4.5+ million sq ft campus in Cedar Rapids, Iowa.

## QUALITY

Rockwell Collins Printed Circuits maintains a customer acceptance rate of 99.5% or better. This has been achieved by strict adherence to the industry standards identified below, achieving the certifications also identified below, and by following the principles of Lean Electronics.

## SPECIFICATIONS

- › ANSI/NCSL Z540-1-1994 (calibrations)
- › J-STD-003
- › IPC-6012 (committee member)
- › IPC-6018 (committee member)
- › IPC-A-600 (committee member)
- › IPC-SM-840 (committee member)
- › MIL-PRF-55110

## CERTIFICATIONS

- › ISO-9001:2000
- › MIL-PRF-55110 QPL
- › Underwriters Laboratory (UL) 94-V0
- › ISO 14001

## Building trust every day.

Rockwell Collins delivers smart communication and aviation electronic solutions to customers worldwide. Backed by a global network of service and support, we stand committed to putting technology and practical innovation to work for you whenever and wherever you need us. In this way, working together, we build trust. Every day.

## For more information contact:

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